

A Project Associate Professor Position
at the Institute for Solid State Physics (ISSP), the University of Tokyo

The ISSP invites outstanding candidates to apply for a project associate professor position in Division of Data-Integrated Materials Science. The division is based on the contract between the University of Tokyo and Toyota Motor Corporation, which will be renewed in April 2022. The objective of the division is to unify experimental and computational approaches to condensed matter physics through data-scientific methods, and to develop a new scheme for predicting and designing innovative functional materials. The successful candidate is expected to play a central role in the new division in cooperation with other staff members as well as colleagues from the partner company.

Applications should include the following documents prepared either in English or Japanese and should be sent by post or alternatively by E-mail to the address below. All the documents must arrive no later than November 26, 2021.

- 1) CV including academic record and professional career
- 2) Summary of research accomplishments (up to three pages)
- 3) Research plan (up to three pages).
- 4) Complete list of publications (mark most important papers)
- 5) 1 copy of each one of the five most important papers

In addition, applicants should arrange for a letter of reference to be sent to the same address.

Postal mail submission:

Send application documents enclosed in an envelope with printing "Application for project associate professor position (DDMS)" in red ink on the front side of the envelope. The documents should be sent by registered mail to the following address.

Administration Office,
The Institute for Solid State Physics,
The University of Tokyo,
5-1-5 Kashiwanoha, Kashiwa,
Chiba 277-8581,
JAPAN

Online submission:

First, send an E-mail to the following E-mail address.

< ISSP general affairs office > issp-jinji@issp.u-tokyo.ac.jp

In doing so, state "Application for project associate professor position (DDMS)" in the subject line. Do not attach any documents. You will receive an instruction E-mail including URL for upload. Then, upload the application documents. Be sure to contact Administrative Office if you do not receive a response within three business days after sending your application documents.

If you have any questions about the application procedure, write to the above address. More general questions should be addressed to Prof. N. Kawashima (kawashima@issp.u-tokyo.ac.jp).